

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHIH WEI LU	01/21/2015
TSUNG-CHIH CHIEN	01/21/2015
HUI-MIN HUANG	01/21/2015
TIEN-I BAO	01/21/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN ROAD 6
<b>Internal Address:</b>	SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14610686
<b>CORRESPONDENCE DATA</b>	
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<b>NAME OF SUBMITTER:</b>	LADONNA JOHNSON
<b>SIGNATURE:</b>	/LaDonna Johnson/
<b>DATE SIGNED:</b>	01/30/2015
<b>Total Attachments: 2</b>	

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**ASSIGNMENT**

WHEREAS, we,

- (1) Chih Wei Lu of Taiwan 300-77, Republic of China
- (2) Tsung-Chih Chien of Taiwan 300-77, Republic of China
- (3) Hui-Min Huang of Taiwan 300-77, Republic of China
- (4) Tien-I Bao of Taiwan 300-77, Republic of China

have invented certain improvements in

**BONDING PAD SURFACE DAMAGE REDUCTION  
IN A FORMATION OF DIGITAL PATTERN GENERATOR**

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and  
 X  filed on January 30, 2015, and assigned application number 14/610,686; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., (“TSMC”), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue

applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Chih Wei Lu

Residence Address: No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park  
Hsin-Chu 300-77, Taiwan, R.O.C.

✓ Dated: Chih-Wei Lu ✓ 01/21/2015  
Inventor Signature

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Inventor Name: Tsung-Chih Chien

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Hsin-Chu 300-77, Taiwan, R.O.C.

✓ Dated: Tsung-Chih Chien ✓ 2015/1/21  
Inventor Signature

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Inventor Name: Hui-Min Huang

Residence Address: No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park  
Hsin-Chu 300-77, Taiwan, R.O.C.

✓ Dated: Hui-Min Huang ✓ 2015/01/21  
Inventor Signature

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Inventor Name: Tien-I Bao

Residence Address: No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park  
Hsin-Chu 300-77, Taiwan, R.O.C.

✓ Dated: 1/21/2015 ✓ Tien-I Bao  
Inventor Signature

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